

DETECTING ANOMALOUS STIFF PILLAR BUMPS FORMED ABOVE A METALLIZATION SYSTEM

ABSTRACT OF THE DISCLOSURE

Generally, the subject matter disclosed herein relates to testing pillar bumps
5 formed on a semiconductor chip so as to detect the presence of anomalous stiff pillar
bumps. One illustrative method disclosed herein includes positioning a test probe (720,
920) adjacent to a side of a pillar bump (703, 903) formed above a metallization system of
a semiconductor chip (702, 902), and performing a lateral force test on the pillar bump
(703, 903) by contacting the side of the pillar bump with the test probe while moving the
10 test probe at a substantially constant speed that is less than approximately 1 $\mu\text{m}/\text{sec}$.

Fig. 7a